



Advance Product Change Notification

201802026A

Issue Date: 08-Mar-2018

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Management Summary

Final Test expansion of the FXLN83xx family from Amkor Korea (ATK3) to NXP Kuala Lumpur, Malaysia site (ATKL).

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input checked="" type="checkbox"/> Test Location	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input checked="" type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input checked="" type="checkbox"/> Test Equipment	<input type="checkbox"/> Electrical spec./Test coverage

**FXLN83xx ATKL
Final Test Transfer**

Details of this Planned Change

NXP Semiconductors announces the final test expansion of the FXLN83xx family to NXP Kuala Lumpur, Malaysia site (ATKL). These products are currently tested at Amkor Korea (ATK3).

Why do we Plan this Change

The test expansion to ATKL is a part of an NXP business decision to assure supply of the FXLN83xx family.

Identification of Affected Products

Product identification does not change

There is no change to the orderable part numbers. NXP will have traceability of the final test site based on the shipping label.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 07-Sep-2018

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Devices will be tested at both ATK3 and ATKL to increase capacity.

Timing and Logistics

The Self Qualification Report will be ready on 01-Jun-2018.

The Final PCN is planned to be issued on: 08-Jun-2018.

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 07-Apr-2018.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Sok Ching Kim Bosiwang Wang

Position Product Engineer

e-mail address kimwang@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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NXP Semiconductors

High Tech Campus, 5656 AG Eindhoven, The Netherlands

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Name	Status	Product Line
FXLN8361QR1	935314846147	FXLN8361QR1	Analog 2 / 8g 3 Axis Acc	VQFN12	RFS	BL Sensors
FXLN8371QR1	935311397147	FXLN8371QR1	Analog 2 / 8g 3 Axis Acc	VQFN12	RFS	BL Sensors